ZMD-Standard

November 2003

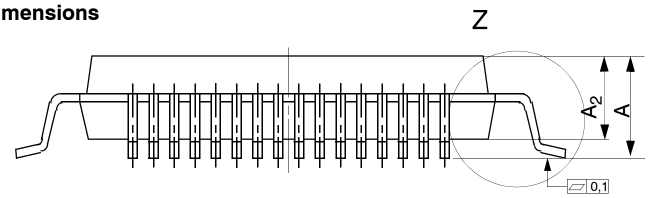
ZMD	**Package PQFP64** (10x10)	**MDS** **755**

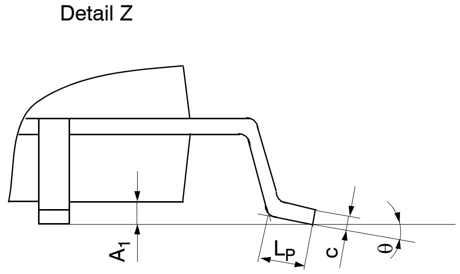
Dimensions in millimetres

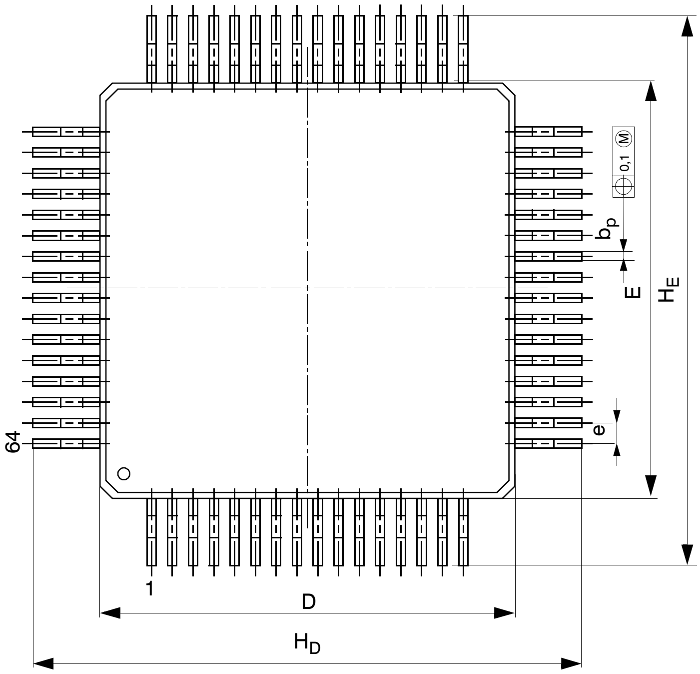
Supersedes
Edition 12.98

Based on JEDEC JEP95: MO-143

1 Dimensions







Dimensions of Sub-Group B1	
e_{nom}	0.50
A_{max}	2.45
b_{Pmin}	0.15
b_{Pmax}	0.30
H_{Emin}	12.95
H_{Emax}	13.45
H_{Dmin}	12.95
H_{Dmax}	13.45
L_{Pmin}	0.73

Dimensions of Sub-Group C1	
A_{1min}	0.10
A_{1max}	0.50
A_{2min}	1.95
A_{2max}	2.10
c_{min}	0.13
c_{max}	0.23
D_{min}	9.90
D_{max}	10.10
E_{min}	9.90
E_{max}	10.10
θ_{min}	0°
θ_{max}	10°

2 Weight	≤ 0,6 g
3 Package Body Material	Low Stress Epoxy
4 Lead Material	FeNi-Alloy or Cu-Alloy
5 Lead Finish	solder plating
6 Lead Form	Z-bends

Zentrum Mikroelektronik Dresden		
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